What is claimed:

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| 1 | 1. | A semiconductor device having a non-volatile memory transistor, |
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| 2 | comprising: | |
| 3 | a semi | conductor layer; |

a floating gate disposed over the semiconductor layer through a first dielectric layer as a gate dielectric layer;

a second dielectric layer that contacts at least a part of the floating gate and is capable of functioning as a tunneling dielectric layer;

a control gate formed over the second dielectric layer; and

an impurity diffusion layer that forms a source region or a drain region formed in the semiconductor layer,

wherein a conduction layer is provided above the floating gate, and the conduction layer entirely overlaps the floating gate.

- A semiconductor device having a non-volatile memory transistor according 2. to claim 1, wherein the conduction layer outwardly protrudes from an end of the floating gate as viewed in a plan view, and a width of a portion of the conduction layer that outwardly protrudes from the end of the floating gate as viewed in a plan view is $0.5\ \mu m$ or smaller.
- A semiconductor device having a non-volatile memory transistor according 3. 1 to claim 1, wherein a side end of the conduction layer formed above the floating gate and an 2 end of the floating gate are aligned with each other. 3
- A semiconductor device having a non-volatile memory transistor according 4. 1 to claim 1, wherein a width of the conduction layer above a region other than a region where 2 the floating gate is formed is narrower than a width of the conduction layer above the region 3 where the floating gate is formed. 4

| 1 | 5. | A semiconductor device having a non-volatile memory transistor according |
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| 2 | to claim 1, w | herein the conduction layer is electrically connected to the semiconductor layer. |

- 6. A semiconductor having a non-volatile memory transistor device, comprising:
- 3 a semiconductor layer;

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- a floating gate disposed over the semiconductor layer through a first dielectric layer

 as a gate dielectric layer;
 - a second dielectric layer that contacts at least a part of the floating gate and is capable of functioning as a tunneling dielectric layer;
- a control gate formed over the second dielectric layer; and
 - an impurity diffusion layer that forms a source region or a drain region formed in the semiconductor layer,
 - wherein a plurality of conduction layers are formed at different levels above the floating gate, and the floating gate is entirely overlapped by the plurality of conduction layers as viewed in a plan view.
- 7. A semiconductor device having a non-volatile memory transistor according to claim 6, wherein at least one of the conduction layers outwardly protrudes from an end of the floating gate as viewed in a plan view, and a width of a portion of the conduction layer that outwardly protrudes from the end of the floating gate as viewed in a plan view is 0.5 μm or smaller.
- 8. A semiconductor device having a non-volatile memory transistor according to claim 6, wherein a side end of the at least one of the conduction layers and an end of the floating gate are aligned with each other.
- 9. A semiconductor device having a non-volatile memory transistor according to claim 6, wherein the conduction layer is electrically connected to the semiconductor layer.

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| 1 | 10. | A semiconductor device having a non-volatile memory transistor, comprising |
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| 2 | a non-volatile | memory transistor including a semiconductor layer, a floating gate disposed |
| 3 | above the sen | niconductor layer, and a control gate formed above the floating gate, wherein a |
| 4 | conduction la | yer is provided vertically above the floating gate at least in a region where the |
| 5 | control gate is | s not disposed vertically above the floating gate. |

- 11. A semiconductor device having a non-volatile memory transistor, comprising a non-volatile memory transistor including a semiconductor layer, a floating gate disposed above the semiconductor layer, and a control gate formed above the floating gate, wherein a conduction layer is provided above the non-volatile memory transistor and a portion of the conduction layer is located vertically above the floating gate, and
- a width of the conduction layer located vertically above the floating gate is formed to be greater than a width of the floating gate.
- 12. A semiconductor device having a non-volatile memory transistor according to claim 11, wherein a width of the conduction layer located other than vertically above the floating gate is formed to be smaller than a width of the conduction layer located vertically above the floating gate.
- 1 13. A semiconductor device having a non-volatile memory transistor according 2 to claim 12, wherein the conduction layer is a wiring layer.
- 1 14. A semiconductor device having a non-volatile memory transistor according 2 to claim 13, wherein the wiring layer is a lowermost wiring layer.

| 1 | 15. A semiconductor device having a non-volatile memory transistor, comprising | ıg |
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| 2 | non-volatile memory transistor including a semiconductor layer, a floating gate disposed | |
| 3 | bove the semiconductor layer, and a control gate disposed above the floating gate, | |
| 4 | wherein a plurality of conduction layers having a multiple layered structure are | |
| 5 | provided above the non-volatile memory transistor, and | |
| 6 | at least one conduction layer among the plurality of conduction layers is provided | |
| 7 | rertically above the floating gate at least in a region where the control gate is not disposed | |
| 8 | rertically above the floating gate. | |

- 1 16. A semiconductor device having a non-volatile memory transistor according 2 to claim 15, where the conduction layers are wiring layers.
- 1 17. A semiconductor device having a non-volatile memory transistor according to claim 15, further comprising:
- a first dielectric layer that defines a gate dielectric layer disposed between the semiconductor layer and the floating gate;
- a second dielectric layer that contacts at least a part of the floating gate and is capable of functioning as a tunneling dielectric layer; and
 - an impurity diffusion layer that forms a source region or a drain region formed in the semiconductor layer.
- 1 18. A semiconductor device having a non-volatile memory transistor according 2 to claim 1, wherein the non-volatile memory transistor comprises a first circuit region, and 3 wherein the semiconductor device further comprises a second circuit region mix-mounted 4 therein.
- 1 19. A semiconductor device having a non-volatile memory transistor according 2 to claim 18, wherein the second circuit region includes at least a logic circuit.

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| 1 | 20. A semiconductor device having a non-volatile memory transistor according |
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| 2 | to claim 10, further comprising: |
| 3 | a first dielectric layer that defines a gate dielectric layer disposed between the |
| 4 | semiconductor layer and the floating gate; |
| 5 | a second dielectric layer that contacts at least a part of the floating gate and is |
| 6 | capable of functioning as a tunneling dielectric layer; and |
| 7 | an impurity diffusion layer that forms a source region or a drain region formed in the |
| 8 | semiconductor layer, |
| | |
| 1 | 21. A semiconductor device having a non-volatile memory transistor according |
| 2 | to claim 15, wherein the non-volatile memory transistor comprises a first circuit region, and |
| 3 | wherein the semiconductor device further comprises a second circuit region mix-mounted |
| 4 | therein. |
| | |
| 1 | 22. A semiconductor device having a non-volatile memory transistor according |
| 2 | to claim 21, wherein the second circuit region includes at least a logic circuit. |
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| 1 | 23. A semiconductor device having a non-volatile memory transistor, comprising |
| 2 | a semiconductor layer; |
| 3 | a floating gate disposed over the semiconductor layer through a first dielectric layer |
| 4 | comprising a gate dielectric layer; |
| 5 . | a second dielectric layer that contacts at least a part of the floating gate and is |
| 6 | capable of functioning as a tunneling dielectric layer; |

one or more conduction layers formed over the floating gate, the floating gate

including an upper surface, wherein a line normal to any portion of the upper surface will

a control gate formed over the second dielectric layer; and

contact at least one of the one or more conduction layers over the floating gate.

| 1 | 24. A method for manufacturing a semiconductor device having a non-volatile | |
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| 2 | memory transistor, comprising: | |
| 3 | forming a first dielectric layer comprising a gate dielectric layer on a substrate; | |
| 4 | forming a floating gate over the gate dielectric layer; | |
| 5 | forming a second dielectric layer that contacts at least a part of the floating gate and | |
| 6 | is capable of functioning as a tunneling dielectric layer; | |
| 7 | forming a control gate over the second dielectric layer; | |
| 8 | forming an impurity diffusion layer that forms a source region or a drain region in | |
| 9 | the semiconductor layer; and | |
| 10 | forming a conduction layer above the floating gate so that a portion of the | |
| 11 | conduction layer is positioned vertically above the floating gate, where the portion of the | |
| 12 | conduction layer overlaps the entire floating gate. | |
| | | |
| 1 | 25. A method for manufacturing a semiconductor device having a non-volatile | |
| 2 | memory transistor, comprising: | |
| 3 | forming a floating gate above a semiconductor layer; | |
| 4 | forming a control gate above the floating gate; and | |
| 5 | forming a conduction layer vertically above the floating gate at least in a region | |
| 6 | where the control gate is not disposed vertically above the floating gate. | |
| | | |

26. A method as in claim 25, comprising forming the conduction layer to have a width greater than that of the floating gate in a region where the conduction layer is disposed vertically above the floating gate.

| 1 | 27. A method for manufacturing a semiconductor device having a non-volatile |
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| 2 | memory transistor, comprising: |
| 3 | forming a floating gate above a semiconductor layer; |
| 4 | forming a control gate above the floating gate, |
| 5 | forming a plurality of conduction layers having a multiple layered structure above |
| 6 | the non-volatile memory transistor, and |
| 7 | wherein at least one of the conduction layers is formed vertically above the floating |
| 8 | gate at least in a region where the control gate is not disposed vertically above the floating |
| 9 | gate |